

Please replace the paragraph beginning at page 13, line 8, with the following rewritten paragraph:

--I. Introduction

The vertically-connected stripline structure described herein comprises a stack of substrate layers. A substrate "layer" is defined as a substrate including circuitry on one or both sides. A process for constructing such a multilayer structure is disclosed by U.S. Patent Application No. 09/199,675 entitled "Method of Making Microwave, Multifunction Modules Using Fluoropolymer Composite Substrates", filed November 25, 1998, now U.S. Patent No. 6,099,977 to Logothetis et al., incorporated herein by reference. Note that references to "substrate layer" and "metal layer" herein are often referred to as "layer" and "metalization", respectively, in U.S. Patent No. 6,099,977.-

In the claims:

Please cancel claims 1-8 and 17-24 without prejudice.

CONDITIONAL PETITION FOR EXTENSION OF TIME

If any extension of time for this response is required, applicant requests that this be considered a petition therefore. Please charge the required Petition fee to Deposit Account No. 03-1240.

ADDITIONAL FEE

Please charge any insufficiency of fees, or credit any excess to our Deposit Account No. 03-1240.

REMARKS

This Preliminary Amendment has been filed to claim the benefit of the filing date of a parent application and to make reference to an issued patent.

Entry of the amendment and an early favorable action on the merits are respectfully requested.

Respectfully submitted,

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I hereby certify that the foregoing application is being deposited with the United States Postal Service "Express Mail Post Office to Addressee" service with sufficient postage on the date indicated above in an envelope addressed to Box Patent Application, Assistant

Commissioner for Patents, Washington, D C 20231.

on January 23, 2001
CHADBOURNE & PARKE LLP
By: Francis Montgomery
Francis G. Montgomery

VERSION WITH MARKINGS TO SHOW CHANGES MADEIn the specification:

paragraph beginning at page 13, line 8 has been amended as follows:

The vertically-connected stripline structure described herein comprises a stack of substrate layers. A substrate "layer" is defined as a substrate including circuitry on one or both sides. A process for constructing such a multilayer structure is disclosed by U.S. Patent Application No. 09/199,675 entitled "Method of Making Microwave, Multifunction Modules Using Fluoropolymer Composite Substrates", filed November 25, 1998, now U.S. Patent No. 6,099,977 to Logothetis et al., incorporated herein by reference. Note that references to "substrate layer" and "metal layer" herein are often referred to as "layer" and "metalization", respectively, in U.S. Patent [Application] No. [09/199,675] 6,099,977.

In the claims:

Claims 1-8 and 17-24 have been canceled